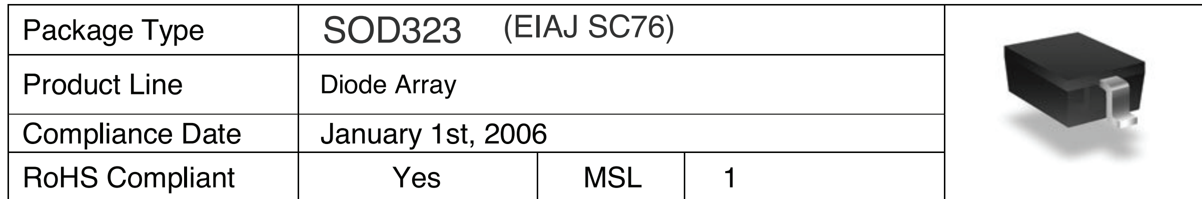
MATERIAL DECLARATION SHEET



Package Type	SOD323 (EIAJ SC76)		
Product Line	Diode Array		
Compliance Date	January 1st, 2006		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.0027	Fused Silica (SiO_2)	60676-86-0	87.70	43.92	50.08
				Epoxy resin	na	5.00	2.50	
				Epoxy CN	29690-82-2	2.00	1.00	
				Phenol resin	na	5.00	2.50	
				Carbon Black	1333-86-4	0.30	0.15	
2	Leadframe	Copper alloy	0.0021	Copper	7440-50-8	94.56	36.75	38.87
				Iron	7439-89-6	2.23	0.87	
				Zinc	7440-66-6	0.01	0.00	
				Phosphorous	7723-14-0	0.03	0.01	
				Silver (Plating)	7440-22-4	3.17	1.23	
3	Chip	Silicon	0.0004	Silicon	7440-21-3	93.73	6.70	7.15
				Aluminium	7429-90-5	3.05	0.22	
				Nickel	7440-02-0	3.08	0.22	
				Gold	7440-57-5	0.13	0.01	
4	Die Attach	Silver epoxy	0.000080	Silver	7440-22-4	75.00	1.12	1.50
				Epoxy	9003-36-5	25.00	0.37	
5	Bond wires	Gold	0.00004	Gold	7440-57-5	100.00	0.83	0.83
6	Terminal Finish	Matte Tin	0.00008	Matte Tin	7440-31-5	100.00	1.41	1.57
		Total Weight	0.005400					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society